T N	Number	Hits	Search Text	DB	Time stamp
<del>  -</del>	vuimer	nics 0	"20030030153"	USPAT	2004/07/11 19:09
					l '
-		1	"20030030153"	USPAT;	2004/07/11 19:32
1	İ	_		US-PGPUB	,
-		2	"6018462"	USPAT;	2004/07/11 19:34
				US-PGPUB	
_		1		USPAT	2004/07/11 19:33
_	1	1		USPAT	2004/07/11 19:34
l _		1		USPAT	2004/07/11 19:34
		1		USPAT	2004/07/11 19:34
_		1		USPAT	2004/07/11 19:34
-		_			1
-		1039147	pad with multi\$4 with (under or lower)	USPAT;	2004/07/11 19:35
İ			layer	US-PGPUB	, ,
-		1038997	pad with multi\$4 near (under or lower)	USPAT;	2004/07/11 19:36
			layer	US-PGPUB	
			pad with multi\$4 near (under or lower)	USPAT	2004/07/11 19:36
1 -			near layers		
_		33	pad with multi\$4 with (under or lower)	USPAT	2004/07/11 19:49
1		33	near layers		
l _		1598	pad with multi\$4 near layers	USPAT	2004/07/11 20:10
-		47	pad with multi94 hear layers   and	USPAT	2004/07/11 20:10
-		4 /	'*	USFAI	2004/0//11 20.10
		-	257/781		0004/07/11 00 00
-		9	"5378927"	USPAT	2004/07/11 20:00
-		203	pad with multi\$4 near layers with (solder	USPAT	2004/07/11 20:00
			or ball or bump)		
-		145	pad with multi\$4 near layers with (solder	USPAT	2004/07/11 20:01
Į.					
_		26	(pad with multi\$4 near layers) and	USPAT	2004/07/11 20:12
			257/782		
		787	257/782	USPAT	2004/07/11 20:51
-		1296	257/779	USPAT	2004/07/11 20:51
-					2004/07/11 20:52
-		1108	257/779 and solder	USPAT	
-		71	257/779 and solder and pad with (lower or	USPAT	2004/07/11 20:57
			bottom or multi\$4) near (layer or film)		
-		126	(257/779 or 257/780 or 257/781) and solder	USPAT	2004/07/11 21:04
			and pad with (lower or bottom or multi\$4)		
			near (layer or film)		1
-		1	<u>-</u>	USPAT	2004/07/11 20:59
_		1		USPAT	2004/07/11 21:00
l _		1		USPAT	2004/07/11 21:00
_		1		USPAT	2004/07/11 21:00
-		1		USPAT	2004/07/11 21:00
-					2004/07/11 21:00
-		1		USPAT	
-		1		USPAT	2004/07/11 21:01
-		2029	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 21:05
			pad with (lower or bottom or multi\$4) near		
			(layers or films)		
-		1123	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 22:05
1			pad with multi\$4 near (layers or films)		1
_		711	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 22:05
			pad with two near (layers or films)	1	
1_		3	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 22:06
-		3	pad with two near (lower or bottom) near	301111	2201, 3., 11 22.00
1		_	(layers or films)	HCDAM	2004/07/11 22:06
-		0	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 22:06
			pad with three near (lower or bottom) near		
			(layers or films)		
-		4	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 22:07
			pad with multi near (lower or bottom) near		
1			(layers or films)		
1_		834	(semiconductor or die or chip or IC) and	USPAT	2004/07/11 22:08
		***	pad with barrier near (layers or films)	!	
1		L	Par ::	.1	<u> </u>